

**5 key reasons**

**die-2-die  
interfaces  
need  
specialty  
I/O and  
ESD**

1

**'die-2-die' (D2D)  
interfaces  
operate  
outside the  
typical GPIO range**

**lower signal voltage &  
reduced drive current**

2

For speed, D2D interfaces  
are designed with thin  
oxide transistors

but those are easily  
damaged during  
ESD events

**3**

**The parasitic capacitance  
of ESD protection in  
traditional GPIOs  
is too high**

**for high bandwidth  
D2D interfaces**

4

When chiplet  
applications target  
thousands of D2D  
connections

the standard I/O pads  
consume too much  
silicon area

5

**ESD clamps integrated in traditional GPIOs are designed for >2kV HBM**

**while D2D interfaces only need a fraction of that.**

# Sofics proven approach

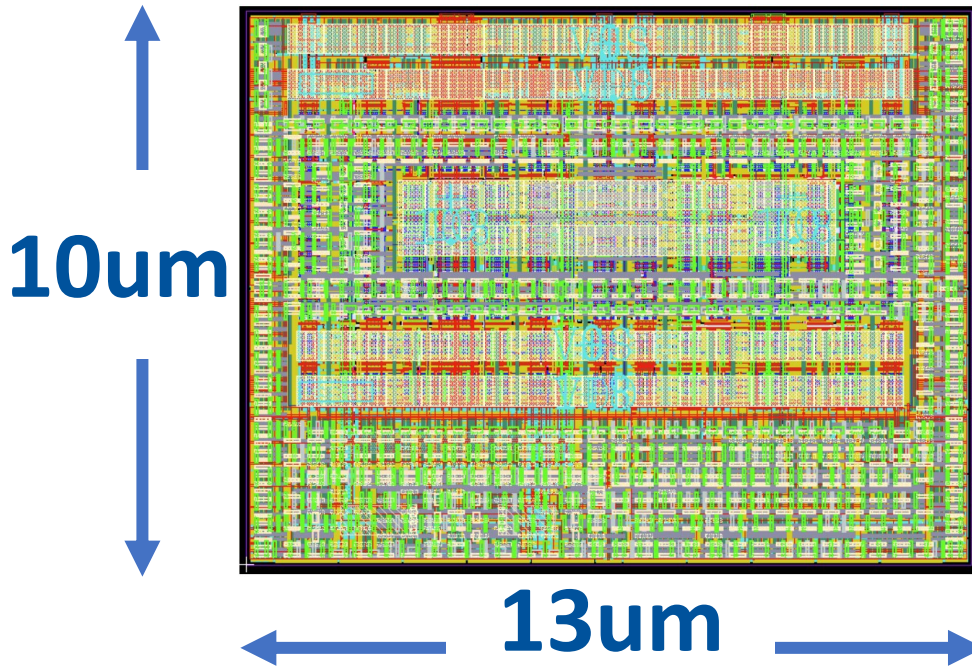
- **ESD protection of sensitive thin oxide circuits**
- **Protection for interfaces at 1V or lower**
- **ESD protection in smaller area**
- **Much reduced parasitic capacitance**
- **Scalable ESD robustness**
- **Proven on many fabs, processes**

# Example on 5nm FinFET

Full local protection for 0.9V I/O

>100V HBM

14fF total capacitance





# Reach out

- For more examples on **other processes**
- To discuss your project



Ehsan



Bart